

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:

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PCN Originator:

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Implementation of change:

Expected 1st Device Shipment Date: 2007/09/30

Earliest Year/Work Week of Changed Product: 0710

Change Type Description: Die Attach Material

Description of Change (From): Change die attach epoxy, Hitachi EN4620K

Description of Change (To): Die attach epoxy, Henkel QMI-519

Reason for Change : Improve MSL level from MSL 3 to MSL 1 and die attached epoxy standardization for all Samsung's Roughen uPPF lead frame

Qual/REL Plan Numbers : Q20070253

And Q20070280 for MLP6X6 MSL L1 Qualification and Q20060359 for MLP5X6 changing of epoxy to QMI519

Qualification :

To qualify MLP 8X8 and MLP 6X6 to MSL -1 by using QMI-519 with Samsung's Roughen NiPdAuAg lead frame. MLP 8X8 and MLP 6X6 are currently qualified as MSL-3 with EN4620K, we are looking in improving the performance of the package.

Qualification Stress Test and Sample Size Detail

Device #1	FDMF8700
Package:	
#Leads:	

Precondition Description:

	Read-points	Sample
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Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
ACLV	X	JESD22-A102	100%RH, 121C	96		77
HAST1	X	JESD22-A110	85%RH, 130C, 0V	96		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500	77

Device #2	FDMF8704
Package:	-1
#Leads:	-1

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
ACLV	X	JESD22-A102	100%RH, 121C	96		77
HAST1	X	JESD22-A110	85%RH, 130C, 0V	96		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500	77

Device #3	FDMF8705
Package:	-1
#Leads:	-1

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
ACLV	X	JESD22-A102	100%RH, 121C	96		77
HAST1	X	JESD22-A110	85%RH, 130C, 0V	96		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500	77

Product Id Description : 8X8/56L 3 DAP MLP , 6X6/40L 3 DAP MLP and 5X6/8L 3 DAP MLP / FDMF8700, FDMF8705 , FDMF6700 and FDMS9620

Affected FSIDs :

FDMF8700	FDMF8705	FDMS9620S
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